GBJ20005 THRU GBJ2010

GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER

REVERSE VOLTAGE: **50 to 1000 VOLTS**

FORWARD CURRENT: **20.0 AMPERE**

FEATURES

· Glass passivated chip junction

· Reliable low cost construction utilizing molded
  plastic technique

· Ideal for printed circuit board

· Low forward voltage drop

· Low reverse leakage current

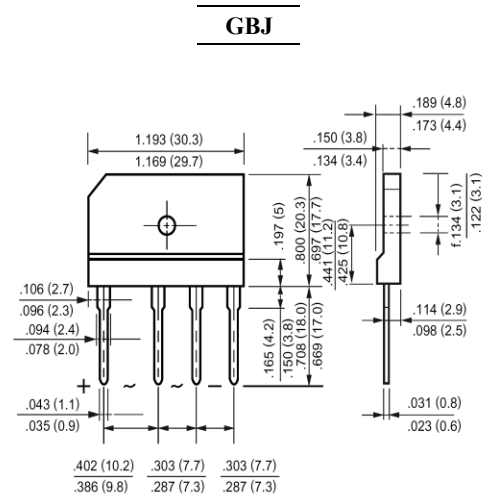· High surge current capability

MECHANICAL DATA

Case: Molded plastic, GBJ

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,
method 208 guaranteed

Mounting position: Any

Weight: 0.23ounce, 6.6gram

GBJ

Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified.

Single phase, half wave, $60H_Z$, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	GBJ20005	GBJ2001	GBJ2002	GBJ2004	GBJ2006	GBJ2008	GBJ2010	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current with Heatsink at T_C=90	$I_{(AV)}$	20.0							Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	250							Amp
Maximum Forward Voltage Drop per Element at 10.0A DC and 25	V_F	1.05							Volts
Maximum Reverse Current at T_A=25 at Rated DC Blocking Voltage T_A=125	I_R	10.0 / 500							uAmp
Typical Junction Capacitance (Note 1)	C_J	60							pF
Typical Thermal Resistance (Note 2)	R_{0JC}	0.8							/W
Operating and Storage Temperature Range	T_J Tstg	-55 to +150							

NOTES:

1- Measured at 1 MH_Z and applied reverse voltage of 4.0 VDC.

2- Thermal Resistance fromn Junction to Case with Device Mounted on 300mm x 300mm x 1.6mmCu Plate Heatsink.

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RATINGS AND CHARACTERISTIC CURVES

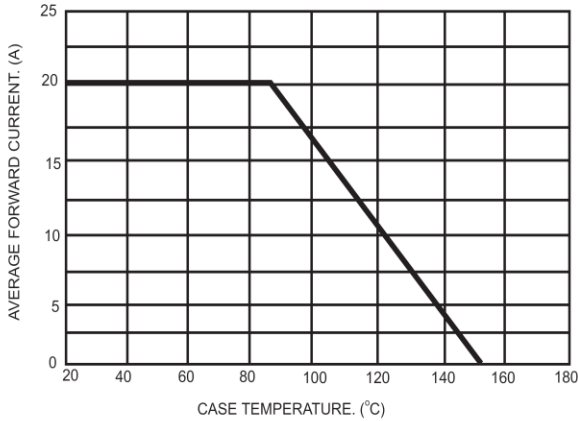FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

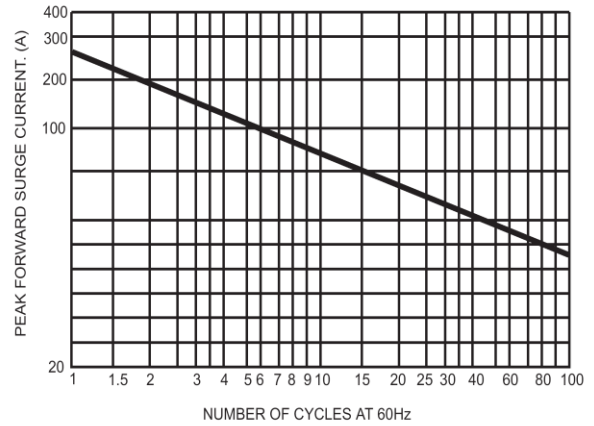FIG.2- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT PER BRIDGE ELEMENT

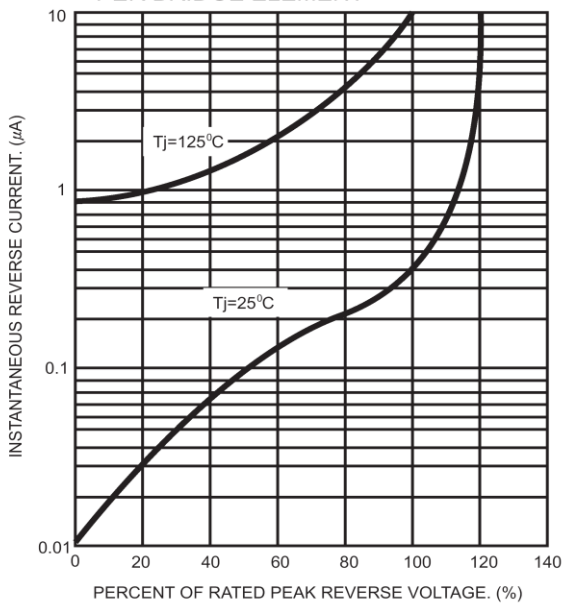FIG.3- TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT
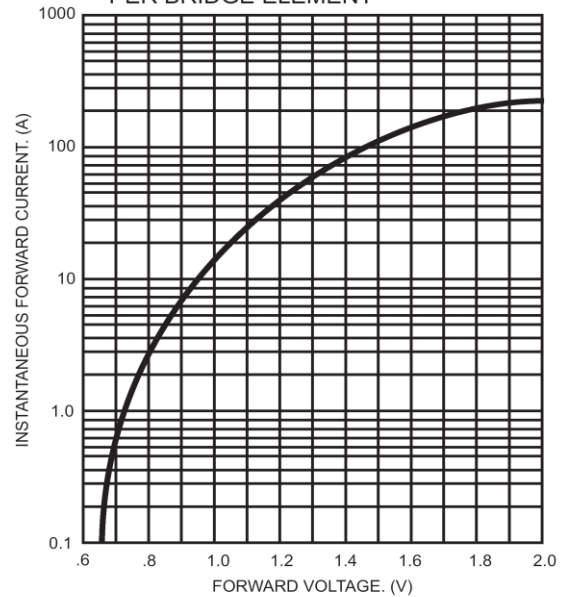

FIG.4- TYPICAL FORWARD CHARACTERISTICS PER BRIDGE ELEMENT

FIG.5- TYPICAL TRANSIENT THERMAL IMPEDANCE

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